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SAMZO		REAC/ROHS								REV	ECN NO	DESCRIPTION	DESIGN	APPROVAL	DATE												
										A1	NEW	Replace frame			2018.06.12												
E																E											
D	P. C. B MOUNTING PATTERN DIMENSION the following soldering are recommended for reflow soldering															D											
C	C 4 B 14 1 1 1 0 A B C D E F G H A. 系列:C-2.7*3.0mm B. 贴装方式:4-立式贴片 C. 引脚规格:B-4PIN D. 操作高度:14-1.4mm E:操作力度:1-180gf F:操作寿命:1-100,000/次 G:固定方式:1-无住 H:物料编码:0-常规 主要技术参数、性能 The Main Thchnology Performance <table><tr><td>额定电流、电压 Rate voltage, current</td><td>50mA DC12V</td></tr><tr><td>接触电阻 Contact resistance</td><td>≤50mΩ</td></tr><tr><td>按力 Operating force</td><td>±40gf</td></tr><tr><td>行程 Travel</td><td>0.20±0.10mm</td></tr><tr><td>绝缘电阻 Insulated resistance</td><td>≥100MΩ</td></tr><tr><td>介电强度 Dielectric strength</td><td>≥250VAC/1min</td></tr></table>															额定电流、电压 Rate voltage, current	50mA DC12V	接触电阻 Contact resistance	≤50mΩ	按力 Operating force	±40gf	行程 Travel	0.20±0.10mm	绝缘电阻 Insulated resistance	≥100MΩ	介电强度 Dielectric strength	≥250VAC/1min
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CIRCUIT DIAGRAM